L Number	Hits	Search Text	DB	Time stamp
1	22569	current adj collector	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:19
2	2289	(current adj collector) with (etch$4 or rough$5 or remov$4 or beam or mill$4 or plasma ion)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:01
3	83	((current adj collector) with (etch$4 or rough$5 or remov$4 or beam or mill$4 or plasma ion)) with diffus$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:18
4	29108	current adj collect$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:19
5	302	(current adj collect$4) with (silicon or si)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:19
6	10	((current adj collect$4) with (silicon or si)) with diffus$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:23
7	38235	429/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:23
8	40	429/$.ccls. and (si silicon) adj electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:33
9	5752	(current adj collector) and 429/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:33
10	15	((current adj collector) and 429/$.ccls.) and (429/$.ccls. and (si silicon) adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:33